ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and N	Afg Informat	ion			
upplier Informa	ation														
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
nsemi										2023-0	2023-06-08				
Contact Name		Title - Contact			1	Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewar	rds	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Represen	ıtative*	Title - Representative			1	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewar	rds	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Requester	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date Version Manufacturing S		Manufacturing Site		Weight*	UOM	Unit Type		
		MDB6S S/P_BR M		S/P_BR MDIP PN	P_BR MDIP PN 1A 600V		2023-06-08			TSCBE		89.837	mg	Each	
	Proccess Information														
8		, and the same of		-STD-020 MS	SL Rating	Peak Process Body Ter					ature Numb	per of Reflow Cyc	eles		
Matte Tin	(Sn) - annealed	C	CU Alloy	1			260		C	30	seco	nds 3			
omments															
	me at peak temperature														
or more information	n regarding material co	mposition]	please refer to	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.849	mg	A	Lead Oxide (PbO)	1317-36-8	7c	0.139	mg
			Supplier	Silicon (Si)	7440-21-3		2.71	mg
Die Attach Solder	1.821	mg	Supplier	Silver (Ag)	7440-22-4		0.0455	mg
			A	Lead (Pb)	7439-92-1	7a	1.6844	mg
			Supplier	Tin (Sn)	7440-31-5		0.091	mg
Lead Frame	39.956	mg	Supplier	Iron (Fe)	7439-89-6		0.056	mg
			Supplier	Copper (Cu)	7440-50-8		39.9	mg
Mold Compound-Black	44.4		Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.44	mg
			Supplier	Carbon Black (C)	1333-86-4		0.133	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.332	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.188	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.307	mg
Plating	0.441	mg	Supplier	Tin (Sn)	7440-31-5		0.441	mg
Wire Bond - Cu	0.37	mg	Supplier	Copper (Cu)	7440-50-8		0.37	mg